# Product End-of-Life Disassembly Instructions

**Product Category:** Notebooks and Tablet PCs

**Marketing Name / Model**
[List multiple models if applicable.]

<table>
<thead>
<tr>
<th>Name / Model #2</th>
<th>Name / Model #3</th>
<th>Name / Model #4</th>
<th>Name / Model #5</th>
</tr>
</thead>
<tbody>
<tr>
<td>HP ProBook 5330m Notebook PC</td>
<td></td>
<td></td>
<td></td>
</tr>
</tbody>
</table>

**Purpose:** The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

## 1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm Mother board, Touch pad, RAM, WWAN</td>
<td>4</td>
</tr>
<tr>
<td>Batteries</td>
<td>All types including standard alkaline and lithium coin or button style batteries Coin cell battery, Battery pack</td>
<td>2</td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries</td>
<td>0</td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps LCD panel</td>
<td>1</td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants weighing &gt; 25 grams (not including PCBs or PCAs already listed as a separate item above)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner</td>
<td>Include the cartridges, print heads, tubes, vent chambers, and service stations.</td>
<td>0</td>
</tr>
<tr>
<td>Components and waste containing asbestos</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Components, parts and materials containing</td>
<td></td>
<td>0</td>
</tr>
</tbody>
</table>
refractory ceramic fibers
Components, parts and materials containing radioactive substances 0

2.0 Tools Required
List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Description #1</td>
<td>Screwdriver</td>
</tr>
<tr>
<td>Description #2</td>
<td></td>
</tr>
<tr>
<td>Description #3</td>
<td></td>
</tr>
<tr>
<td>Description #4</td>
<td></td>
</tr>
<tr>
<td>Description #5</td>
<td></td>
</tr>
</tbody>
</table>

3.0 Product Disassembly Process
3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Disassemble Battery Door
2. Disassemble Main Battery
3. Dis-fasten keyboard screw*3
4. Pull out keyboard membrane
5. Pull out keyboard backlit FPC
6. Remove keyboard
7. Dis-fasten Base Door screw*3
8. Remove Base Door
9. Dis-fasten HDD BKT screw*3
10. Remove HDD BKT module
11. Dis-fasten HDD screw*4
12. Remove HDD
13. Pull out LCD cable
14. Pull out antenna cables
15. Dis-fasten WLAN screw*1
16. Remove WLAN module
17. Dis-fasten WWAN screw*1
18. Remove WWAN module
19. Dis-fasten BASE screw*11
20. Dis-fasten KB Deck screw*3
21. Pull out FFC*4 (Power, Touchpad, Fingerprint, Hot-key boards)
22. Disassemble KB Deck
23. Pull out FFC*1 (Audio board)
24. Remove Fingerprint module
25. Dis-fasten daughter boards screw*3 (Power, Hot-key, Audio)
26. Remove daughter boards*3 (Power, Hot-key, Audio)
27. Dis-fasten Fan screw*4
28. Pull out fan cable
29. Remove Fan module
30. Pull out speaker cable
31. Pull out Bluetooth cable
32. Dis-fasten motherboard screw*3
33. Remove motherboard
34. Dis-fasten thermal module screw*4
35. Remove thermal module
36. Remove coin battery

PSG instructions for this template are available at EL-MF877-01
37. Pull out DC cable
38. Remove DC cable
39. Dis-fasten speaker screw*4
40. Remove speaker -L & -R
41. Dis-fasten Hinge screw*4
42. Remove LCD module
43. Remove LCD bezel
44. Dis fasten Hinge Cap -L & -R screw*2
45. Remove Hinge Cap -L & -R
46. Dis fasten LCD module screw*4
47. Pull out LCD cable & camera cable
48. Remove LCD module
49. Dis fasten LCD BKT -L & -R screw*7
50. Remove LCD BKT -L & -R

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

LCD panel disassembly procedure

Remove tape, cover film and screw

Remove bezel

Remove Cell

Remove films

Remove LGP & white sheet

Separate LED reflector from frame

Remove tape

Separate LED light bar

LED light bar